

In the Specification:

Please amend the specification as follows.

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a' line 28: delete "Figure 3 is a schematic diagram" and insert Figures 3A-3D are schematic diagrams.

In the Claims:

[Please amend the claims as follows.]

a2 1. (Once Amended) An imaging device for imaging radiation, said imaging device comprising a semiconductor substrate including an array of detector cells which generate charge in response to incident radiation and a corresponding readout semiconductor substrate including an array of readout cells, said readout cells being connected to corresponding detector cells by low temperature solder bumps, wherein said low temperature solder bumps comprise lead-tin based solder having a melting point below that of eutectic lead-tin solder.

✓ Please cancel claim 5 without prejudice to or disclaimer of the subject matter contained therein.

13:

~~14:~~ (Once Amended) An imaging system comprising:

a3 an imaging device of imaging radiation, said imaging device comprising an array of detectors which generate charge in response to incident radiation and an array for readout devices connected to corresponding elements of said array of detectors by low temperature solder bumps comprising lead-tin based solder having a melting point below that of eutectic lead-tin solder;